

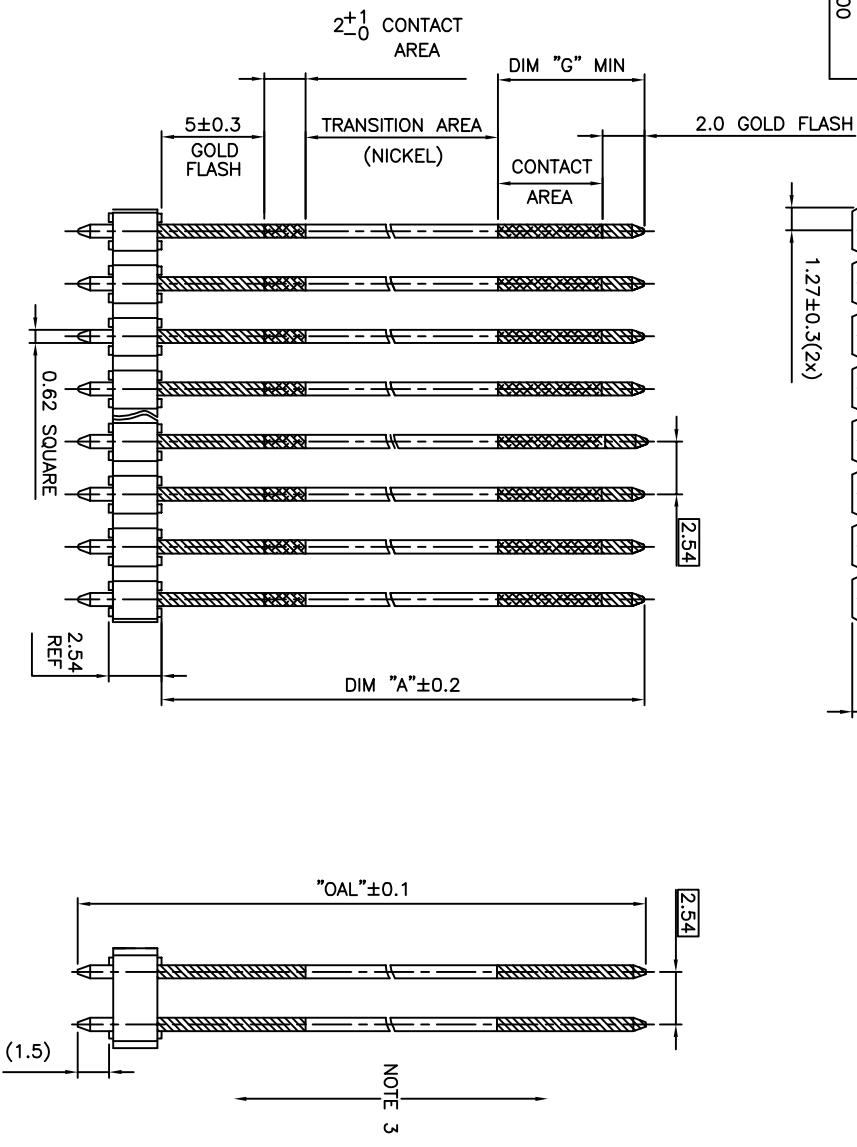
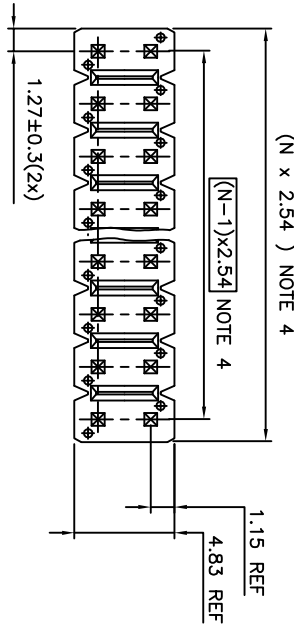
PRODUCT NUMBER
54775-XXX-XXLF

PLATING _____
 1 = 0.76µm GOLD/GXT ON CONTACT AREAS
 1.27µm NICKEL MIN
 6 = 0.76µm GXT (PdNi WITH GOLD FLASH) ON CONTACT AREAS OVER 1.27µm NICKEL MIN (ALTERNATIVE 0.76µm GOLD/GXT ON CONTACT AREAS)

PIN STYLE	DIM "A"	"OAL"	DIM "G" MIN
01	31.0	35.0	7.00
02	31.0	35.0	10.00

- NOTES:
- HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC; UL94V-0 COLOR: BLACK
 - PIN MATERIAL : PHOSPHOR BRONZE
 - 9N MIN RETENTION IN EITHER DIRECTION
 - TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS PER ROW, N x 2.54 = 20.32mm
 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS

- d - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE,
 b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection		product family	
ltr	ecm no	dr	date	ISO 1302	ISO 406	ISO 1001	mm	title	type
H	F07-0207	LMU	07.06.06	tolerances unless otherwise specified			mm	UNSHR.HEADER	CUSTOMER
J	F08-0148	RTR	08.03.31					STRAIGHT	
K	B-19264	LMU	14.10.31				scale 5:1		
E	F06-0196	LMU	06.06.13	eng'g	U	COMPAGNON	02.03.04		
F	F06-0294	JCO	06.10.09	chr	JCO		02.04.02		
G	F07-0136	JCO	07.02.19	apprd	JCO		02.04.02		
sheet	revision								
index	sheet								